

AEROSPACE MATERIAL SPECIFICATION

SAE

AMS 3731/2B

Issued 1 OCT 1981
Revised 1 JUL 1991

Superseding AMS 3731/2A

Submitted for recognition as an American National Standard

POTTING COMPOUND, EPOXY
Bisphenol A-Type
Filled, Heat Cure, Low CTE
Thermal Shock Resistant

1. SCOPE:

- 1.1 Form: This specification covers a filled epoxy resin formulation, supplied as a two-component system, requiring an oven cure for attainment of maximum properties.
- 1.2 Application: Primarily for use as a potting or sealing material where a low coefficient of thermal expansion is desired.
- 1.3 Classification: Compound is classified as follows:
- Type I - Gray. Resin base supplied white with curing agent black for visual monitoring of uniformity of mixing.
- Type II - Color optional, either natural or colored, as ordered.
- 1.3.1 Type I shall be supplied unless Type II is ordered.

2. APPLICABLE DOCUMENTS: See AMS 3731.

3. TECHNICAL REQUIREMENTS:

- 3.1 Basic Specification: The complete requirements for procuring the product described herein shall consist of this document and the latest issue of the basic specification, AMS 3731.
- 3.2 Material: Shall be an epoxy-based polymer with a filler and a curing agent:
- 3.3 Properties: Compound shall conform to the following requirements:
- 3.3.1 Resin Base Compound Without Curing Agent:

SAE Technical Board Rules provide that: "This report is published by SAE to advance the state of technical and engineering sciences. The use of this report is entirely voluntary, and its applicability and suitability for any particular use, including any patent infringement arising therefrom, is the sole responsibility of the user."

SAE reviews each technical report at least every five years at which time it may be reaffirmed, revised, or cancelled. SAE invites your written comments and suggestions.

- 3.3.1.1 Foaming: The volume of the compound shall not exceed 3 times its original volume when it is de-aired at a pressure lower than 5 Torr (667 Pa) at 20° - 32°C (68° - 90°F).
- 3.3.2 Mixed Uncured Compound: The compound, mixed in accordance with manufacturer's instructions, shall exhibit the following properties:
- 3.3.2.1 Viscosity: Shall be not greater than 8000 centipoises (8.0 Pa·s) at 65°C ± 1 (149°F ± 2), determined within 5 minutes after mixing, using a Brookfield Model LVF viscometer and No. 3 spindle at 6 revolutions per minute.
- 3.3.2.2 Pot Life: Usable life of the compound, defined as the time to attain double the initial viscosity determined in 3.3.2.1, shall be not less than 60 minutes at 65°C ± 1 (149°F ± 2).
- 3.3.2.3 Curing Time: The time required to develop the cured product properties specified in 3.3.3 shall be not more than 16 hours at 65°C ± 1 (149°F ± 2) or not more than 8 hours at 95°C ± 2 (203°F ± 4).
- 3.3.3 Cured Product: The compound, mixed and cured in accordance with manufacturer's instructions, shall exhibit the following properties, determined in accordance with test methods listed in AMS 3731:
- 3.3.3.1 Flexural Strength, minimum 10.0 ksi (68.9 MPa)
- 3.3.3.2 Izod Impact Strength, per unit of notch, minimum 0.30 foot-pound per inch (16 J/M)
- 3.3.3.3 Compressive Strength, minimum 20.0 ksi (138 MPa)
- 3.3.3.4 Insulation Resistance
- 3.3.3.4.1 At 23°C (73°F), minimum 1x10⁶ megohms
- 3.3.3.4.2 At 120°C (248°F), minimum 1x10⁵ megohms
- 3.3.3.4.3 After Hydrolytic Stability Conditioning, minimum 1x10⁴ megohms
- 3.3.3.5 Dielectric Constant at 1 KHz and, 20° - 30°C (68° - 86°F), maximum 5.5
- 3.3.3.6 Dissipation Factor at 1 KHz and, 20° - 30°C (68° - 86°F), maximum 0.04
- 3.3.3.7 Heat Deflection Temperature at 264 psi (1.82 MPa), minimum 88°C (190°F)
- 3.3.3.8 Coefficient of Linear Thermal Expansion, maximum